



High Speed Switching Diode



Forward Current - 250 mA
Reverse Voltage - 100 V

Description

- Power Dissipation of 250mW
- Fast Switching Device (TRR<4nS)
- High Stability and High Reliability
- Low Reverse Leakage

Mechanical Data

- Case: SOD323 Package
- Case Material: "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Terminals: Matte tin plated, solderable per MIL-STD-750, method 2026
- Component in accordance to RoHS
- Halogen Free

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Ordering Information

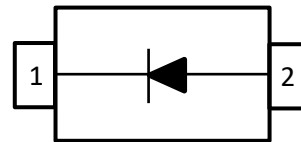
- Package :SOD323
- Reel Size :7 (inches)
- Quantity Per Reel :3,000/Tape & Reel
- Quantity One Box :45,000/Tape & Reel

Package Outline

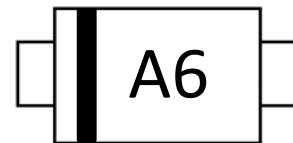


SOD323 Top View

Device Schematic & PIN Configuration



Product Type Marking Code



"A6" = Product Type Marking Code

Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Absolute Ratings

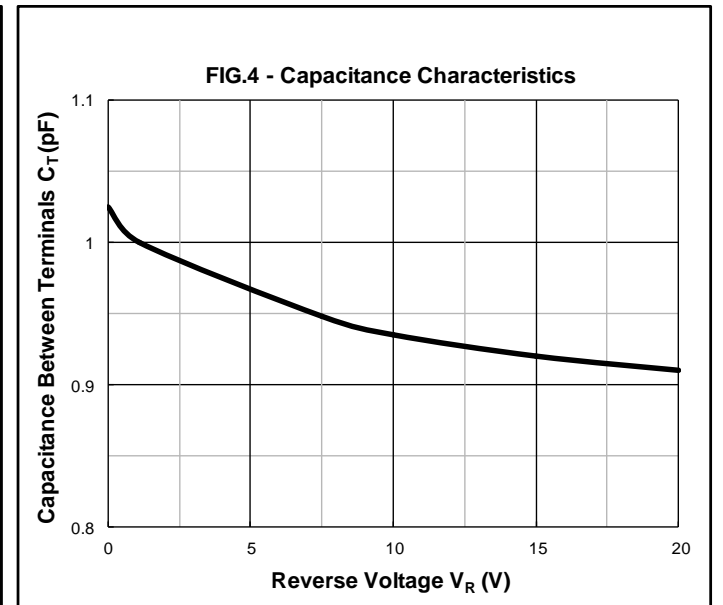
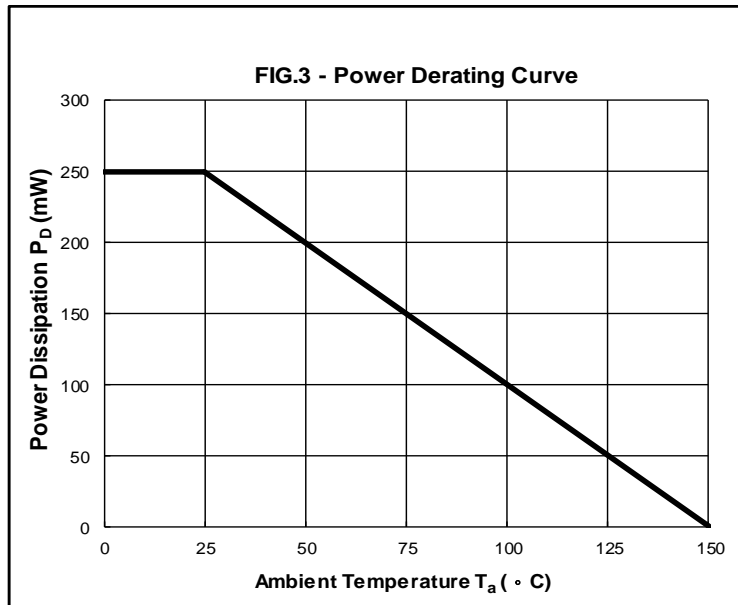
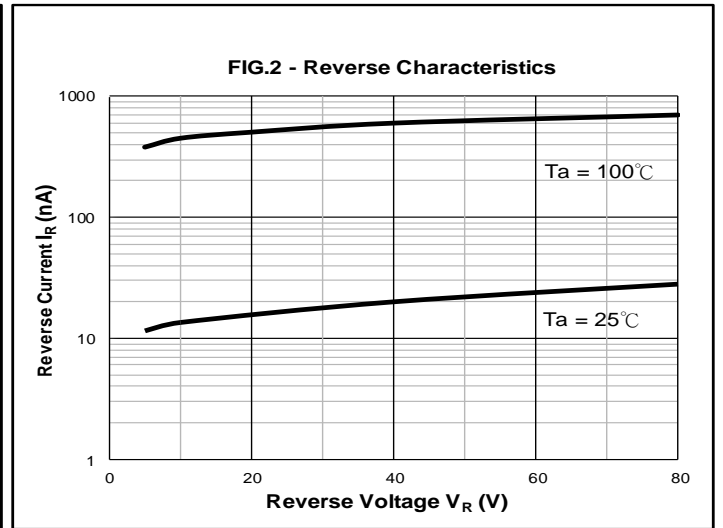
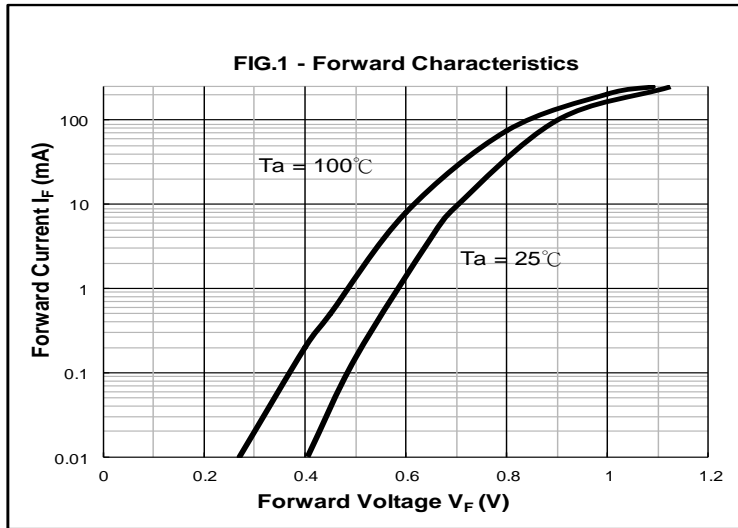
Parameter	Symbol	Value	Unit
Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Peak Forward Surge Current @ $t_p=8.3ms$; $T_A=25^\circ C$	I_{FSM}	2	A
Average Rectified Current	I_o	250	mA
Power Dissipation	P_D	250	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	500	$^\circ C/W$
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_S	-55 to +150	$^\circ C$

Electrical Characteristics

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Reverse Voltage	$I_R=100\mu A$	V_{BR}	100	-	-	V
Reverse Current	$V_R=25V$	I_R	-	-	30	nA
	$V_R=75V$		-	-	1	μA
Forward Voltage	$I_F=1mA$	V_F	-	-	0.71	V
	$I_F=10mA$		-	-	0.85	
	$I_F=50mA$		-	-	1.00	
	$I_F=150mA$		-	-	1.25	
Reverse Recovery Time	$I_F=I_R=10mA$ $I_{RR}=0.1*I_R, R_L=100\Omega$	T_{RR}	-	-	4	ns
Junction Capacitance	$V_R = 0V, F = 1MHz$	C_T	-	-	1.5	pF

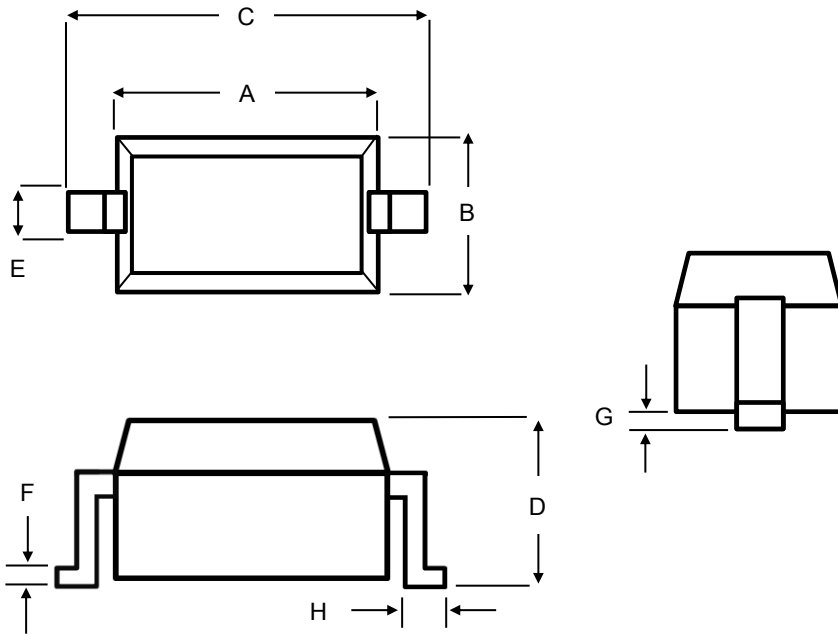


Rating and Characteristic Curves



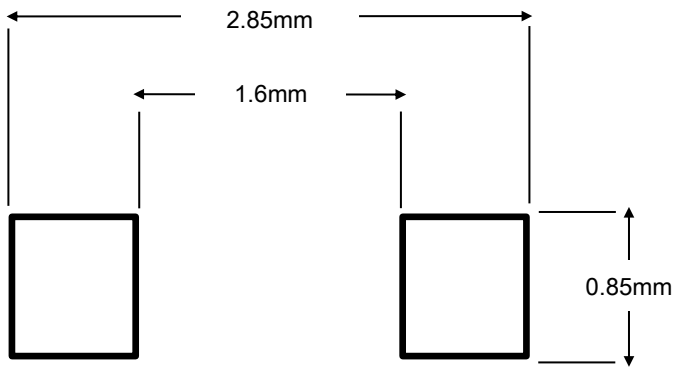


Package Outline Dimensions



SOD323 Package		
Dim	Min	Max
A	1.6	1.8
B	1.2	1.4
C	2.5	2.7
D	-	1.0
E	0.25	0.35
F	0.08	0.15
G	-	0.1
H	0.25	0.4
All Dimensions in mm		

Suggested Soldering Pad Layout



Note:

- 1.The pad layout is for reference purposes only.
- 2.General tolerance $\pm 0.05\text{mm}$



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